

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC61FxxxxxPR-G

Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.528	Silicon	10000	7440-21-3
Leadframe	20.083	Copper	378900	7440-50-8
	0.060	Tin	1100	7440-31-5
	0.050	Zinc	900	7440-66-6
	0.067	Chromium	1300	7440-47-3
	0.802	Silver	15100	7440-22-4
Die attach	0.126	Silver	2400	7440-22-4
	0.032	Epoxy	600	—
Bonding wire	0.030	Gold	600	7440-57-5
Resin	26.652	Silica	502900	60676-86-0
	2.175	Epoxy Resin	41000	—
	1.569	Phenol Resin	29600	—
	0.425	Metal hydroxide	8000	—
Plating	0.400	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."